

MODULE HAVING DUAL-BAND SURFACE ACOUSTIC WAVE  
CIRCUITS AND METHOD OF MANUFACTURING THE SAME

ABSTRACT OF THE DISCLOSURE

A module that contains multiple surface acoustic wave (SAW)  
circuits and a method of manufacturing the module. In one  
embodiment, the module includes: (1) a hermetically-sealable shell  
having first and second terminal sets, (2) a first SAW circuit,  
located within the shell and couplable to the first terminal set,  
that filters signals in a first band of communications frequencies,  
and (3) a second SAW circuit, located within the shell and  
couplable to the second terminal set, that filters signals in a  
second band of communications frequencies.